

High Performance ASIC Cooling Solutions w/Thermal Tape Attachment*

DIGI-KEY PART # **ATS1343-ND**

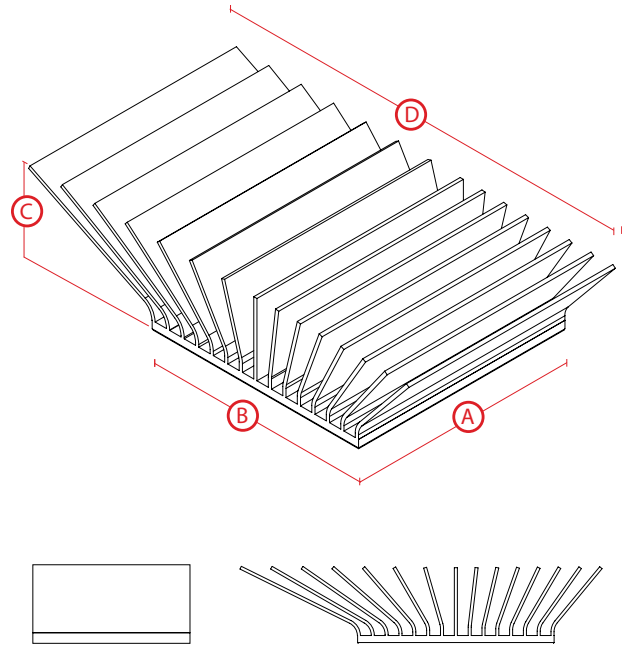
ATS PART # ATS-56012-C3-R0

Features & Benefits

maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

Designed specifically for ASIC package and their unique cooling requirements

Comes preassembled with high performance thermal interface material



Thermal Performance Table

AIR VELOCITY		THERMAL RESISTANCE	
FT/MIN	M/S	°C/W (UNDUCTED)	°C/W (DUCTED)
200	1.0	2.8	1.4
300	1.5	2.1	
400	2.0	1.77	
500	2.5	1.57	
600	3.0	1.43	
700	3.5	1.33	
800	4.0	1.25	

Product Details†

DIMENSION A	DIMENSION B	DIMENSION C§	DIMENSION D	TIM‡	FINISH
42	42	16	62	C675	GOLD-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



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Innovations in Thermal Management®



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